

## 30V /10A Single N Power MOSFET

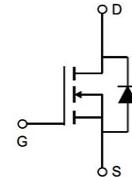
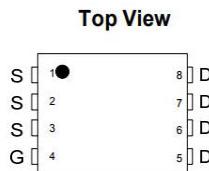
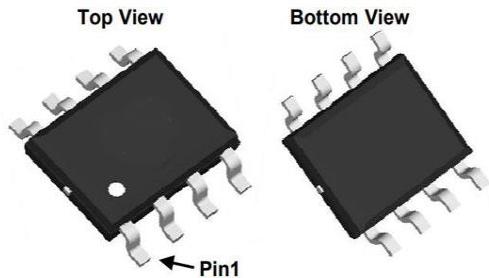
### General Description

30V /10A Single N Power MOSFET

Very low on-resistance RDS(on) @ VGS=4.5 V

Pb-free lead plating; RoHS compliant

<b>V<sub>DS</sub></b>	30	V
<b>R<sub>DS(on),TYP@VGS=10V</sub></b>	18.2	mΩ
<b>R<sub>DS(on),TYP@VGS=4.5</sub></b>	28.6	mΩ
<b>I<sub>D</sub></b>	10	A



Part ID	Package Type	Marking	Tape and reel infomation
SM4496PRL	SOP8	4496	3000



100% UIS Tested  
100% RG Tested

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	20	±V
Continuous Drain Current A	I <sub>D</sub>	10.0	A
		7.5	
Pulsed Drain Current B	I <sub>DM</sub>	16.0	
Avalanche Current G	I <sub>AR</sub>	3.2	
Repetitive avalanche energy L=0.1mH G	E <sub>AR</sub>	7.4	mJ
Power Dissipation A	P <sub>D</sub>	3.1	W
		2	
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient A	R <sub>θJA</sub>	65	97	°C/W
Maximum Junction-to-Ambient A		130	156	°C/W
Maximum Junction-to-Lead c	R <sub>θJL</sub>	39	62	°C/W

## STATIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D = -250\mu A, V_{GS} = 0V$	30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$			1	uA
					5	
$I_{GSS}$	Gate-Body leakage current	$V_{DS} = 0V, V_{GS} = \pm 20V$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.3	1.9	2.5	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10V, I_D=10A$		18.2	26.0	mΩ
		$V_{GS}=4.5V, I_D=10A$		28.6	37.2	
$g_{FS}$	Forward Transconductance	$V_{DS}=5V, I_D=10A$		51		S
$V_{SD}$	Diode Forward Voltage	$I_S=1A, V_{GS}=46V$		0.72	1	V
$I_S$	Maximum Body-Diode Continuous Current				10	A

## DYNAMIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=15V, f=1MHz$		550	671	pF
$C_{oss}$	Output Capacitance			110	135	pF
$C_{rss}$	Reverse Transfer Capacitance			55	65	pF
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$			1.1	Ω

## SWITCHING PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$Q_g(10V)$	Total Gate Charge	$V_{GS}=10V, V_{DS}=15V, I_D=10A$		4.6		nC
$Q_g 4.5V)$	Total Gate Charge			2.3		
$Q_{gs}$	Gate Source Charge			1.54		
$Q_{gd}$	Gate Drain Charge			2.2		
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=10V, V_{DS}=15V, RL=0.75\Omega, R_{GEN}=3\Omega$		11		ns
$t_r$	Turn-On Rise Time			8.8		
$t_{D(off)}$	Turn-Off Delay Time			30.8		
$t_f$	Turn-Off Fall Time			9.9		
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=-8A, dI/dt=500A/\mu s$		22		ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=18A, dI/dt=500A/\mu s$		14		nC

## CAL ELECTRICAL AND THERMAL CHARACTERISTICS

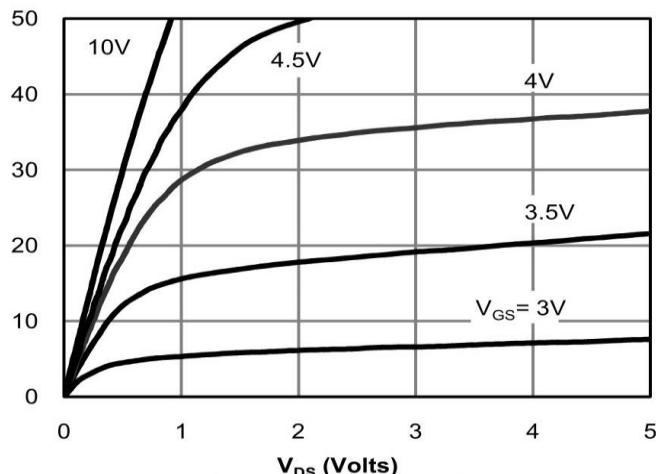


Figure 1: On-Region Characteristics

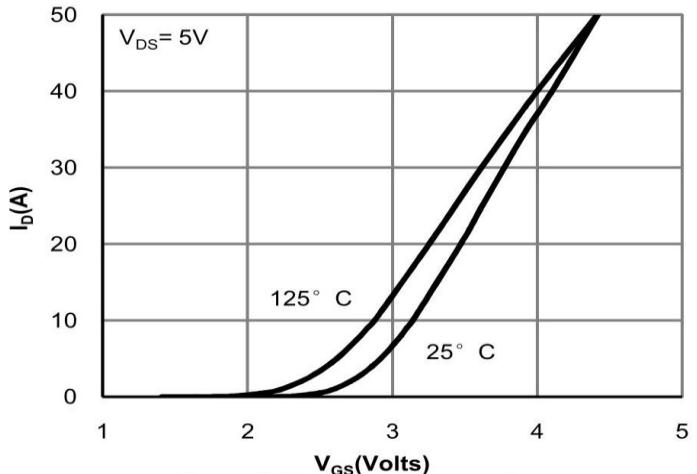


Figure 2: Transfer Characteristics

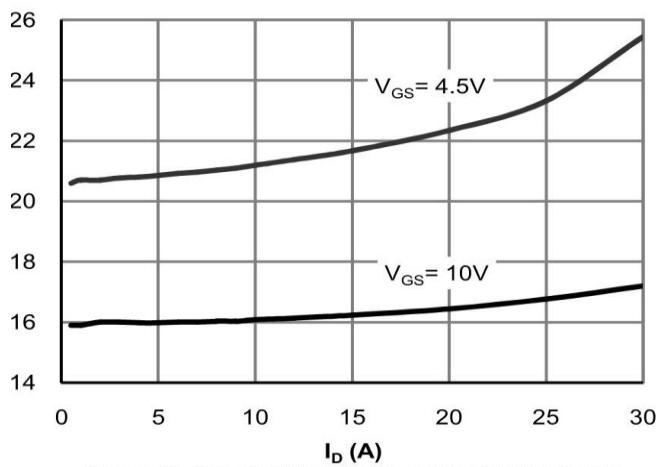


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

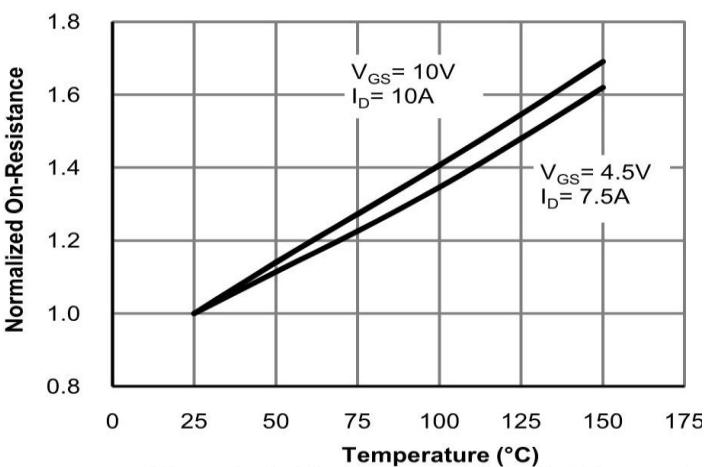
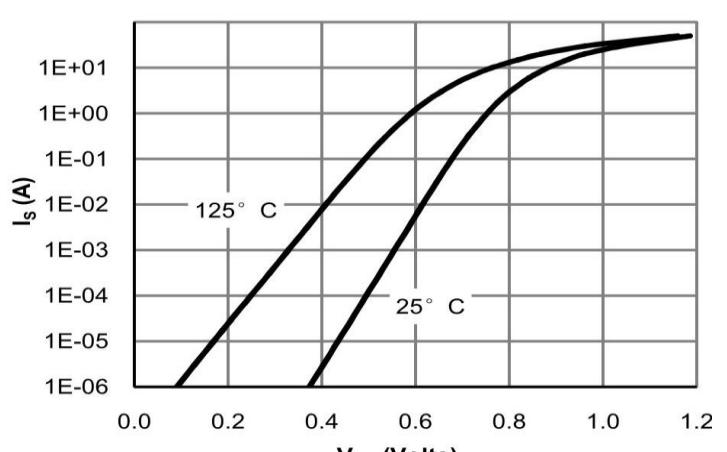
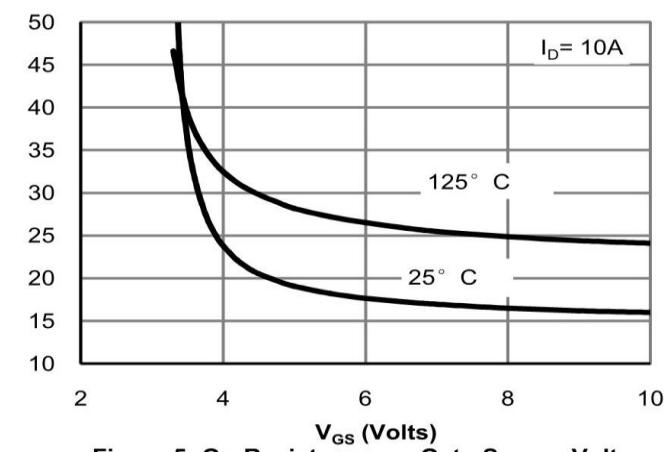
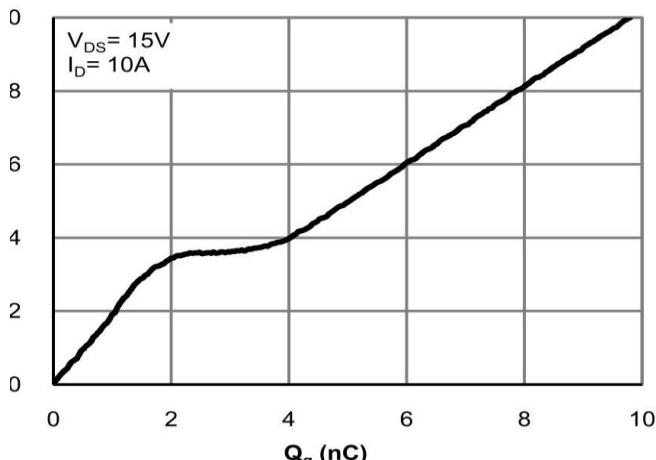


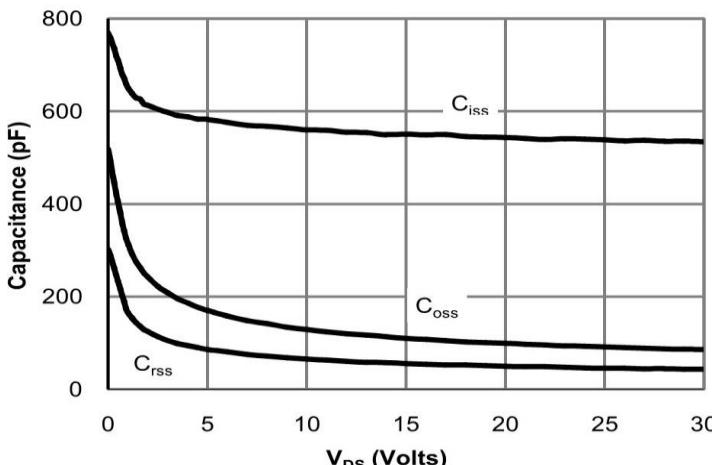
Figure 4: On-Resistance vs. Junction Temperature



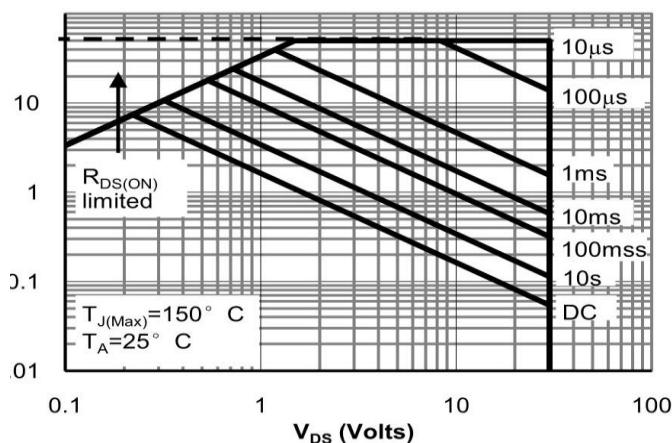
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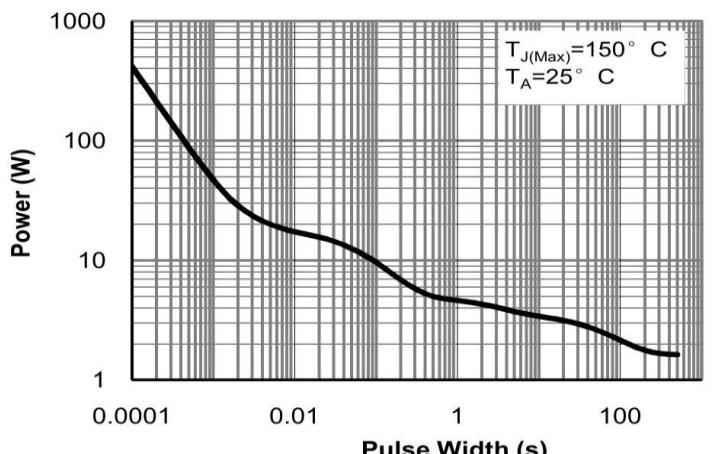
**Figure 7: Gate-Charge Characteristics**



**Figure 8: Capacitance Characteristics**



**Figure 9: Maximum Forward Biased Safe Operating Area (Note E)**



**Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)**

